The SN54125, SN54126, SN74125, SN74126, and SN54LS126A are obsolete and are no longer supplied.

### SN54125, SN54126, SN54LS125A, SN54LS126A, SN74125, SN74126, SN74LS125A, SN74LS126A QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS

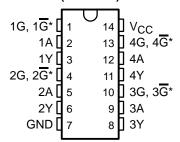
SDLS044A - DECEMBER 1983 - REVISED MARCH 2002

- Quad Bus Buffers
- 3-State Outputs
- Separate Control for Each Channel

#### description

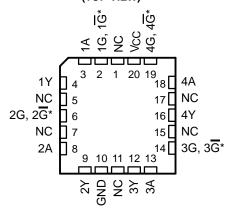
These bus buffers feature three-state outputs that, when enabled, have the low impedance characteristics of a TTL output with additional drive capability at high logic levels to permit driving heavily loaded bus lines without external pullup resistors. When disabled, both output transistors are turned off, presenting a high-impedance state to the bus so the output will act neither as a significant load nor as a driver. The '125 and 'LS125A devices' outputs are disabled when  $\overline{G}$  is high. The '126 and 'LS126A devices' outputs are disabled when G is low.

SN54125, SN54126, SN54LS125A, SN54LS126A...J OR W PACKAGE SN74125, SN74126...N PACKAGE SN74LS125A, SN74LS126A...D, N, OR NS PACKAGE (TOP VIEW)



\*G on '125 and 'LS125A devices; G on 126 and 'LS126A devices

## SN54LS125A, SN54LS126A . . . FK PACKAGE (TOP VIEW)



\*G on '125 and 'LS125A devices; G on 126 and 'LS126A devices NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



The SN54125, SN54126, SN74125, SN74126, and SN54LS126A are obsolete and are no longer supplied.

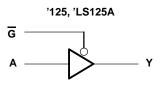
SDLS044A - DECEMBER 1983 - REVISED MARCH 2002

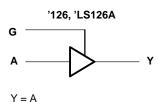
#### **ORDERING INFORMATION**

TA	PACI	KAGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74LS125AN	SN74LS125AN
	PDIF - IN	Tube	SN74LS126AN	SN74LS126AN
		Tube	SN74LS125AD	LS125A
0°C to 70°C	SOIC - D	Tape and reel	SN74LS125ADR	L3125A
0.01070.0	30IC = D	Tube	SN74LS126AD	LS126A
		Tape and reel	SN74LS126ADR	L3120A
	SOP – NS	Tape and reel	SN74LS125ANSR	74LS125A
	30F - N3	Tape and reel	SN74LS126ANSR	74LS126A
	CDIP – J	Tube	SN54LS125AJ	SN54LS125AJ
_55°C to 125°C	CDIP = J	Tube	SNJ54LS125AJ	SNJ54LS125AJ
-55 0 10 125 0	CFP – W	Tube	SNJ54LS125AW	SNJ54LS125AW
	LCCC – FK	Tube	SNJ54LS125AFK	SNJ54LS125AFK

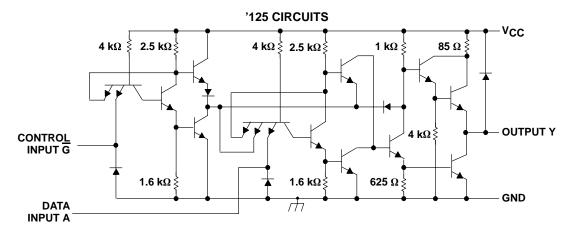
<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

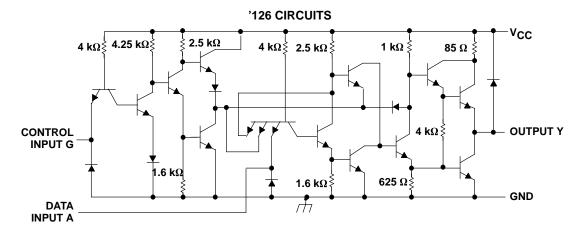
### logic diagram (each gate)





#### schematics (each gate)





## absolute maximum ratings over operating free-air temperature (unless otherwise noted)<sup>†</sup> ('125 and '126)

Supply voltage, V <sub>CC</sub> (see Note 1)	7 V
Input voltage, V <sub>I</sub>	5.5 V
Package thermal impedance, θ <sub>JA</sub> (see Note 2):N package	80°C/W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

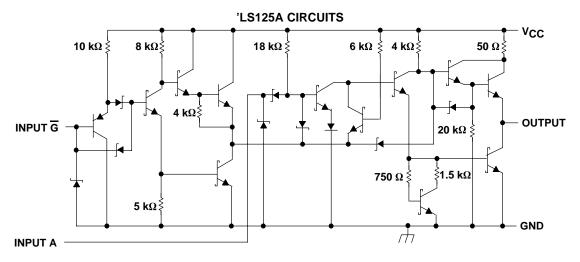
<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values are with respect to network ground terminal.

2. The package termal impedance is calculated in accordance with JESD 51-7.



#### schematics (each gate)



#### **'LS126A CIRCUITS VCC** 8 kΩ≶ 18 kΩ≶ 12 kΩ ≥ 18 $k\Omega$ $6 \text{ k}\Omega$ 4 kΩ: $50 \Omega$ **INPUT G OUTPUT** 20 k $\Omega$ 750 Ω ≶ ∮1.5 kΩ 5 k $\Omega$ **GND** Ш **INPUT A**

Resistor values shown are nominal.

# absolute maximum ratings over operating free-air temperature (unless otherwise noted)† ('LS125A and 'LS126A)

Supply voltage, V <sub>CC</sub> (see Note 1)	
Input voltage, V <sub>I</sub>	
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D package	86°C/W
N package	80°C/W
NS package	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values are with respect to network ground terminal.
  - 2. The package termal impedance is calculated in accordance with JESD 51-7.



## SN54125, SN54126, SN54LS125A, SN54LS126A, SN74125, SN74126, SN74LS125A, SN74LS126A QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS

SDLS044A - DECEMBER 1983 - REVISED MARCH 2002

#### recommended operating conditions

			SN54125 SN54126		9, 9,		UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-2			-5.2	mA
lOL	Low-level output current			16			16	mA
TA	Operating free-air temperature	-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS <sup>†</sup>				SN54125 SN54126				UNIT
					TYP‡	MAX	MIN	TYP‡	MAX	
VIK	$V_{CC} = MIN,$	I <sub>I</sub> = -12 mA				-1.5			-1.5	V
Vou	$V_{CC} = MIN,$	V <sub>IH</sub> = 2 V,	$I_{OH} = -2 \text{ mA}$	2.4	3.3					٧
VOH	V <sub>IL</sub> = 0.8 V		$I_{OH} = -5.2 \text{ mA}$				2.4	3.1		V
V <sub>OL</sub>	$V_{CC} = MIN,$	V <sub>IH</sub> = 2 V,	$V_{IL} = 0.8 V$ ,			0.4			0.4	V
VOL	$I_{OL} = 16 \text{ mA}$					0.4			0.4	V
1	$V_{CC} = MAX$	$V_{IH} = 2 V$	$V_0 = 2.4 \text{ V}$			40			40	μΑ
loz	$V_{IL} = 0.8 V$		$V_0 = 0.4 \text{ V}$			-40			-40	μΑ
lį	$V_{CC} = MAX$ ,	$V_{I} = 6.5 \text{ V}$				1			1	mA
lіН	$V_{CC} = MAX$ ,	V <sub>I</sub> = 2.4 V				40			40	μΑ
I <sub>IL</sub>	$V_{CC} = MAX$ ,	V <sub>I</sub> = 0.4 V				-1.6			-1.6	mA
l <sub>OS</sub> §	V <sub>CC</sub> = MAX			-30		<del>-</del> 70	-28		-70	mA
laa	$V_{CC} = MAX$		'125		32	54		32	54	mA
Icc	(see Note 3)		'126		36	62		36	62	IIIA

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 3: Data inputs = 0 V; output control = 4.5 V for '125 and 0 V for '126.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see Figure 1)

PARAMETER	TEST CON	SN54125 SN74125			SN54126 SN74126			UNIT	
			MIN	TYP	MAX	MIN	TYP	MAX	
<sup>t</sup> PLH	$R_1 = 400 \Omega$	C <sub>I</sub> = 50 pF		8	13		8	13	ns
<sup>t</sup> PHL	11 = 400 22,	OL = 30 pi		12	18		12	18	113
<sup>t</sup> PZH	$R_1 = 400 \Omega$	C <sub>I</sub> = 50 pF		11	17		11	18	ns
<sup>t</sup> PZL	TC_ = 400 32,	OL = 30 pi		16	25		16	25	113
<sup>t</sup> PHZ	$R_1 = 400 \Omega$	C <sub>I</sub> = 5 pF		5	8		10	16	ns
tPLZ	NC = 400 32,	о <u>г</u> = 3 рі		7	12		12	18	115



<sup>&</sup>lt;sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time.

#### recommended operating conditions

			SN54LS125A SN54LS126A			SN74LS125A SN74LS126A			
		MIN	NOM	MAX	MIN	NOM	MAX		
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
V <sub>IL</sub>	Low-level input voltage			0.7			0.8	V	
ЮН	High-level output current			-1			-2.6	mA	
loL	Low-level output current			12			24	mA	
TA	Operating free-air temperature	-55		125	0		70	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITION	ıst		54LS125  54LS126		_	74LS125 74LS126		UNIT	
				MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX		
VIK	$V_{CC} = MIN,$	$I_{I} = -18 \text{ mA}$				-1.5			-1.5	V	
Voн	$V_{CC} = MIN,$	$V_{IL} = 0.7 V$ ,	$I_{OH} = -1 \text{ mA}$	2.4						V	
VOH	V <sub>IH</sub> = 2 V	V <sub>IL</sub> = 0.8 V	$I_{OH} = -2.6 \text{ mA}$				2.4			V	
		$V_{IL} = 0.7 V$ ,	$I_{OL} = 12 \text{ mA}$		0.25	0.4					
VOL	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V	$V_{IL} = 0.8 V$ ,	$I_{OL} = 12 \text{ mA}$					0.25	0.4	V	
	I VIH - Z V	V <sub>IL</sub> = 0.8 V,	$I_{OL} = 24 \text{ mA}$					0.35	0.5	.	
		V <sub>II</sub> = 0.7 V	V <sub>O</sub> = 2.4 V			20					
	V <sub>CC</sub> = MAX,	VIL = 0.7 V	V <sub>O</sub> = 0.4 V			-20					
loz	V <sub>IH</sub> = 2 V,	V., 0.9.V	V <sub>O</sub> = 2.4 V						20	μΑ	
		V <sub>IL</sub> = 0.8 V	V <sub>O</sub> = 0.4 V						-20		
lį	$V_{CC} = MAX$ ,	V <sub>I</sub> = 7 V				0.1			0.1	mA	
lН	$V_{CC} = MAX$ ,	V <sub>I</sub> = 2.7 V				20			20	μΑ	
1	$V_{CC} = MAX$ ,	'LS125A-G input	S			-0.2			-0.2	mA	
II∟	V <sub>I</sub> = 0.4 V	'LS125A-A input	s; 'LS126A All inputs			-0.4			-0.4	mA	
I <sub>OS</sub> §	V <sub>CC</sub> = MAX			-40		-225	-40		-225	mA	
	V <sub>CC</sub> = MAX		'LS125A		11	20		11	20	mA	
lcc	(see Note 4)		'LS126A		12	22		12	22	IIIA	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see Figure 1)

PARAMETER	TEST CONDITIONS			SN54LS125A SN74LS125A			SN54LS126A SN74LS126A			
			MIN	TYP	MAX	MIN	TYP	MAX		
<sup>t</sup> PLH	R <sub>L</sub> = 667 Ω,	C <sub>L</sub> = 45 pF		9	15		9	15	ns	
<sup>t</sup> PHL	11 = 007 32,	OL = 40 βl		7	18		8	18	113	
<sup>t</sup> PZH	$R_L = 667 \Omega$	C <sub>L</sub> = 45 pF		12	20		16	25	ns	
<sup>t</sup> PZL	11 = 007 32,	Ο <u>Γ</u> = 40 βι		15	25		21	35	113	
<sup>t</sup> PHZ	$R_L = 667 \Omega$ ,	C <sub>I</sub> = 5 pF			20			25	- ns	
<sup>t</sup> PLZ	11 = 007 32,	ο[ - σ μι			20			25		

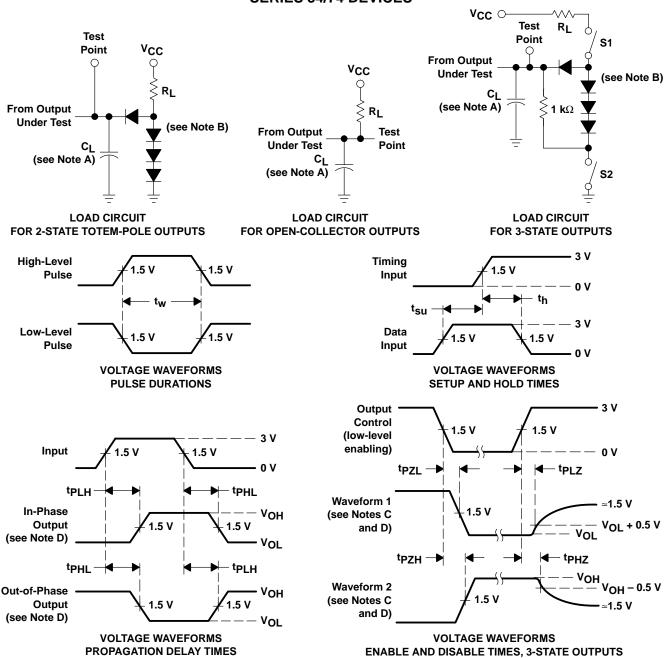


 $<sup>\</sup>ddagger$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 4: Data inputs = 0 V; output control = 4.5 V for 'LS125A and 0 V for 'LS126A.

#### PARAMETER MEASUREMENT INFORMATION **SERIES 54/74 DEVICES**



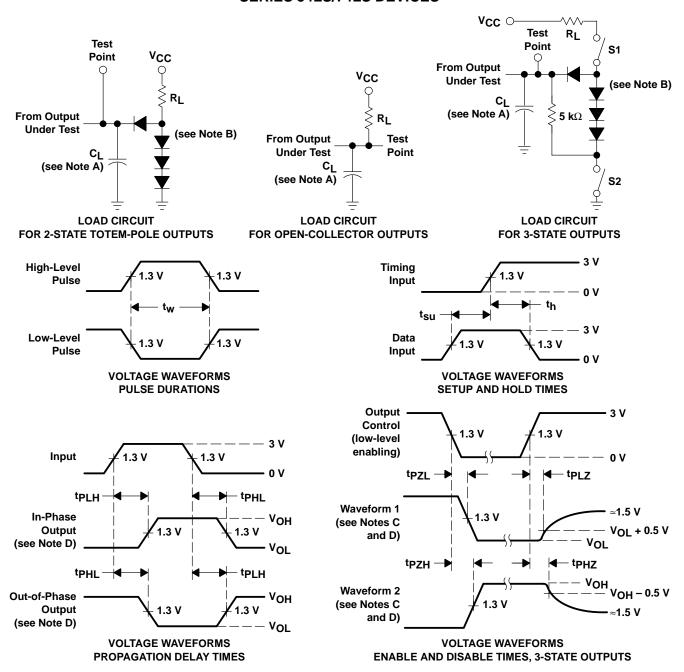
NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. All diodes are 1N3064 or equivalent.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. S1 and S2 are closed for tpLH, tpHL, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
- E. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O \approx 50 \Omega$ ;  $t_r$  and  $t_f \leq$  7 ns for Series 54/74 devices and  $t_r$  and  $t_f \le 2.5$  ns for Series 54S/74S devices.
- F. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION SERIES 54LS/74LS DEVICES



- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. All diodes are 1N3064 or equivalent.
  - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - D. S1 and S2 are closed for tpLH, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
  - E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
  - F. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O \approx 50~\Omega$ ,  $t_f \leq$  1.5 ns,  $t_f \leq$  2.6 ns.
  - G. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms



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#### **PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
JM38510/32301B2A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 32301B2A
JM38510/32301B2A.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 32301B2A
JM38510/32301BCA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 32301BCA
JM38510/32301BCA.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 32301BCA
JM38510/32301BDA	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 32301BDA
JM38510/32301BDA.A	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 32301BDA
M38510/32301B2A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 32301B2A
M38510/32301BCA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 32301BCA
M38510/32301BDA	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 32301BDA
SN54LS125AJ	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS125AJ
SN54LS125AJ.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS125AJ
SN74LS125AD	Obsolete	Production	SOIC (D)   14	-	=	Call TI	Call TI	0 to 70	LS125A
SN74LS125AD.B	Obsolete	Production	SOIC (D)   14	-	=	Call TI	Call TI	0 to 70	LS125A
SN74LS125ADBR	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A
SN74LS125ADBR.A	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A
SN74LS125ADR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A
SN74LS125ADR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A
SN74LS125ADR.B	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A
SN74LS125ADRE4	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A
SN74LS125AN	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS125AN
SN74LS125AN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS125AN
SN74LS125ANSR	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS125A



-55 to 125

N/A for Pkg Type

**SNPB** 

19-Aug-2025

SNJ54LS125AW



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Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74LS125ANSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS125A
SN74LS125ANSR.B	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS125A
SN74LS126AD	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	0 to 70	LS126A
SN74LS126AD.B	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	0 to 70	LS126A
SN74LS126ADR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS126A
SN74LS126ADR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS126A
SN74LS126AN	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS126AN
SN74LS126AN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS126AN
SN74LS126ANSR	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS126A
SN74LS126ANSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS126A
SNJ54LS125AJ	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS125AJ
SNJ54LS125AJ.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS125AJ
SNJ54LS125AW	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS125AW

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Active

SNJ54LS125AW.A

25 | TUBE

Production

CFP (W) | 14

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

### **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN54LS125A, SN74LS125A:

Catalog: SN74LS125A

Military: SN54LS125A

NOTE: Qualified Version Definitions:

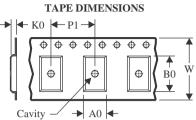
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS125ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LS125ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS125ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LS126ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS126ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1



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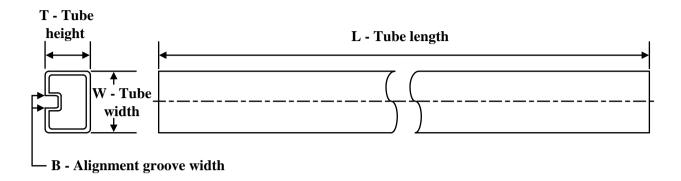
\*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS125ADBR	SSOP	DB	14	2000	353.0	353.0	32.0
SN74LS125ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LS125ANSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74LS126ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LS126ANSR	SOP	NS	14	2000	353.0	353.0	32.0



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#### **TUBE**



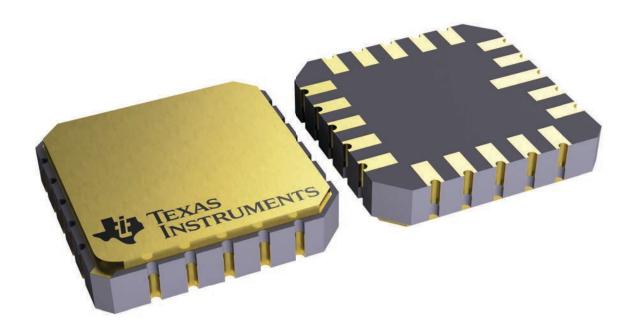
\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/32301B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/32301B2A.A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/32301BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/32301BDA.A	W	CFP	14	25	506.98	26.16	6220	NA
M38510/32301B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/32301BDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS125AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS125AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS125AN.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS125AN.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS126AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS126AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS126AN.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS126AN.A	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS125AW	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54LS125AW.A	W	CFP	14	25	506.98	26.16	6220	NA

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



**INSTRUMENTS** www.ti.com

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

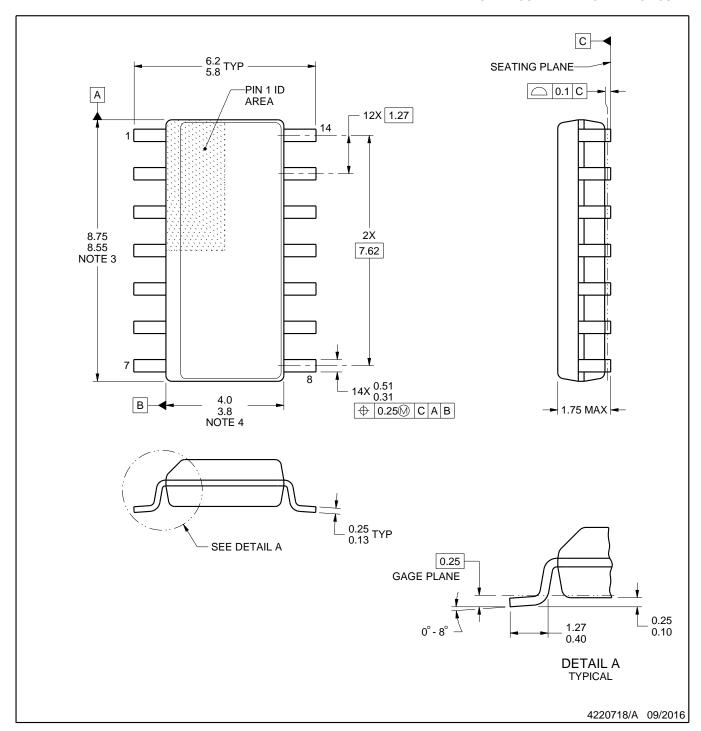


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



#### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE

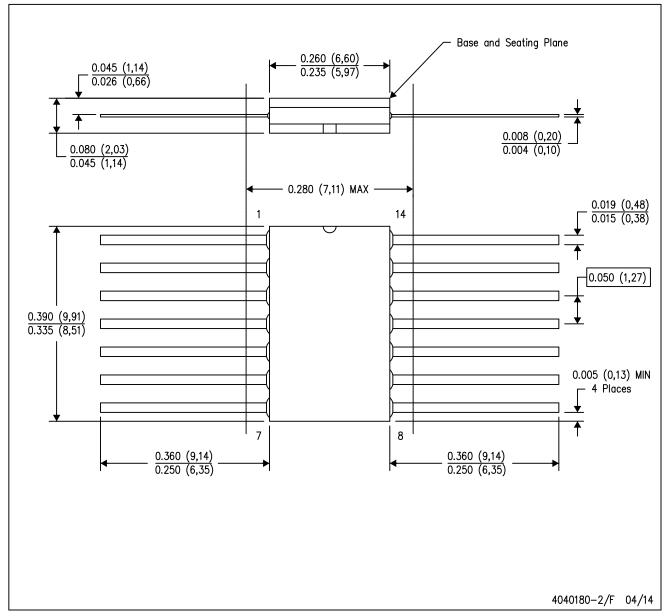


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## W (R-GDFP-F14)

## CERAMIC DUAL FLATPACK

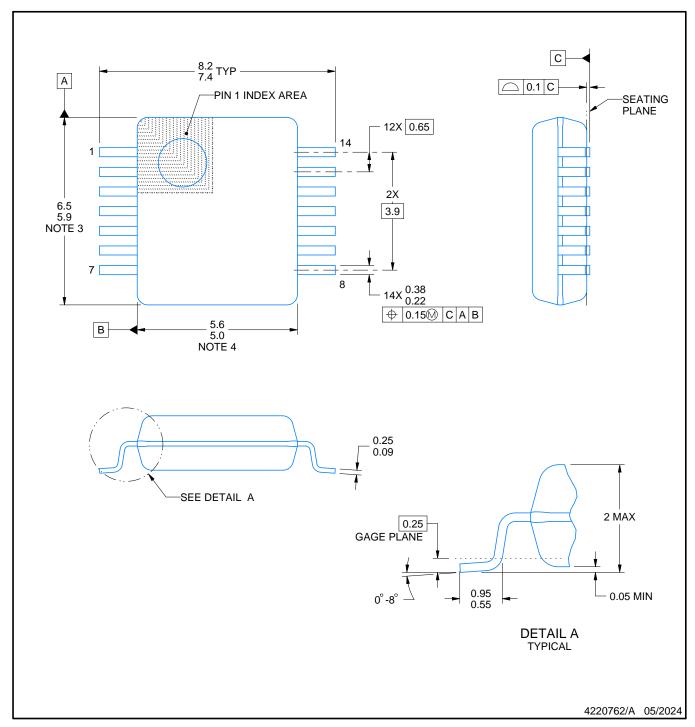


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14





SMALL OUTLINE PACKAGE



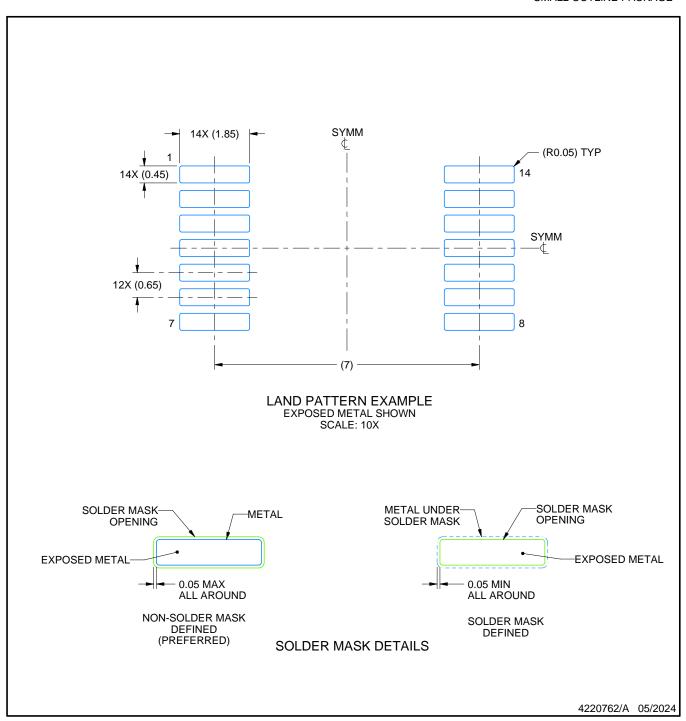
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-150.



SMALL OUTLINE PACKAGE

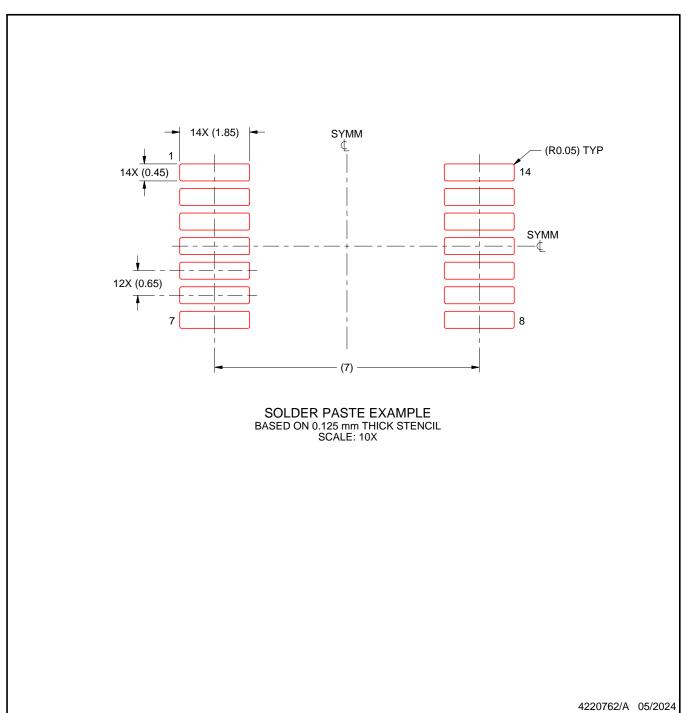


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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